Product Change Notification - KSRA-08NNFY461

Date: 31 Aug 2017

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Notification subject: CCB 2800 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products of 200K wafer technology available in 44L QFN (8x8x0.9mm) package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire and C194 lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
September 18, 2017 (1738)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

	December 2016					→	August 2017					September 2017			
Workweek	49	50	51	52	53		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date					X										
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
December 29, 2016: Issued initial notification.
January 11, 2017: Re-issued initial notification to change the lead frame material from A194 to C194 for consistency.
August 18, 2017: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on September 18, 2017
August 31, 2017: Re-issued final notification to update subject from Initial Notice to Final Notice.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-08NNFY461_Affected CPN.pdf
PCN_KSRA-08NNFY461_Qual Report.pdf
PCN_KSRA-08NNFY461_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

KSRA-08NNFY461 - CCB 2800 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-08NNFY461
CATALOG_PART_NBR
PIC16F1717-E/ML
PIC16F1717-I/ML
PIC16F1717T-I/ML
PIC16F1719-E/ML
PIC16F1719-I/ML
PIC16F1719T-I/ML
PIC16F1784-E/ML
PIC16F1784-I/ML
PIC16F1784T-I/ML
PIC16F1787-E/ML
PIC16F1787-I/ML
PIC16F1787T-I/ML
PIC16F1787T-I/ML020
PIC16F1789-E/ML
PIC16F1789-I/ML
PIC16F1789T-I/ML
PIC16F1934-E/ML
PIC16F1934-I/ML
PIC16F1934T-I/ML
PIC16F1937-E/ML
PIC16F1937-I/ML
PIC16F1937T-I/ML
PIC16F1939-E/ML
PIC16F1939-I/ML
PIC16F1939T-I/ML
PIC16F707-E/ML
PIC16F707-I/ML
PIC16F707T-I/ML
PIC16F724-E/ML
PIC16F724-I/ML
PIC16F724T-I/ML
PIC16F727-E/ML
PIC16F727-I/ML
PIC16F727T-I/ML
PIC16LF1717-E/ML
PIC16LF1717-I/ML
PIC16LF1717T-I/ML
PIC16LF1719-E/ML
PIC16LF1719-I/ML
PIC16LF1719T-I/ML
PIC16LF1784-E/ML
PIC16LF1784-I/ML
PIC16LF1784T-I/ML

KSRA-08NNFY461 - CCB 2800 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-08NNFY461
CATALOG_PART_NBR
PIC16LF1787-E/ML
PIC16LF1787-I/ML
PIC16LF1787T-I/ML
PIC16LF1789-E/ML
PIC16LF1789-I/ML
PIC16LF1789T-I/ML
PIC16LF1934-E/ML
PIC16LF1934-I/ML
PIC16LF1934T-I/ML
PIC16LF1937-E/ML
PIC16LF1937-I/ML
PIC16LF1937T-I/ML
PIC16LF1939-E/ML
PIC16LF1939-I/ML
PIC16LF1939T-I/ML
PIC16LF707-E/ML
PIC16LF707-I/ML
PIC16LF707T-I/ML
PIC16LF724-E/ML
PIC16LF724-I/ML
PIC16LF724T-I/ML
PIC16LF727-E/ML
PIC16LF727-I/ML
PIC16LF727-I/MLC01
PIC16LF727T-I/ML
PIC16LF727T-I/MLC01
PIC18F43K20-E/ML
PIC18F43K20-I/ML
PIC18F43K20T-I/ML
PIC18F43K22-E/ML
PIC18F43K22-I/ML
PIC18F43K22T-I/ML
PIC18F44K20-E/ML
PIC18F44K20-I/ML
PIC18F44K20T-I/ML
PIC18F44K22-E/ML
PIC18F44K22-I/ML
PIC18F44K22T-I/ML
PIC18F45K20-E/ML
PIC18F45K20-I/ML
PIC18F45K20-I/MLC01
PIC18F45K20-I/MLC05
PIC18F45K20T-I/ML

KSRA-08NNFY461 - CCB 2800 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-08NNFY461
CATALOG_PART_NBR
PIC18F45K20T-I/MLC01
PIC18F45K20T-I/MLC05
PIC18F45K22-E/ML
PIC18F45K22-I/ML
PIC18F45K22T-I/ML
PIC18F45K80-E/ML
PIC18F45K80-H/ML
PIC18F45K80-I/ML
PIC18F45K80T-E/ML
PIC18F45K80T-I/ML
PIC18F46K20-E/ML
PIC18F46K20-I/ML
PIC18F46K20T-E/ML
PIC18F46K20T-I/ML
PIC18F46K22-E/ML
PIC18F46K22-I/ML
PIC18F46K22T-E/ML
PIC18F46K22T-I/ML
PIC18F46K80-E/ML
PIC18F46K80-H/ML
PIC18F46K80-I/ML
PIC18F46K80T-E/ML
PIC18F46K80T-I/ML
PIC18LF43K22-E/ML
PIC18LF43K22-I/ML
PIC18LF43K22T-I/ML
PIC18LF44K22-E/ML
PIC18LF44K22-I/ML
PIC18LF44K22T-I/ML
PIC18LF45K22-E/ML
PIC18LF45K22-I/ML
PIC18LF45K22T-I/ML
PIC18LF45K80-I/ML
PIC18LF45K80T-I/ML
PIC18LF46K22-E/ML
PIC18LF46K22-I/ML
PIC18LF46K22T-I/ML
PIC18LF46K80-I/ML
PIC18LF46K80T-I/ML
PIC24F16KA304-I/ML
PIC24F16KA304T-I/ML
PIC24F16KM204-E/ML
PIC24F16KM204-I/ML

KSRA-08NNFY461 - CCB 2800 Final Notice: Qualification of CuPdAu bond wire for selected products of 200K wafer technology available in 16L QFN (3x3x0.9mm) package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-08NNFY461
CATALOG_PART_NBR
PIC24F32KA304-E/ML
PIC24F32KA304-I/ML
PIC24F32KA304T-I/ML
PIC24FV08KM204-I/ML
PIC24FV16KA304-I/ML
PIC24FV16KA304T-I/ML
PIC24FV16KM104-I/ML
PIC24FV16KM204-I/ML
PIC24FV32KA304-E/ML
PIC24FV32KA304-I/ML
PIC24FV32KA304T-I/ML